

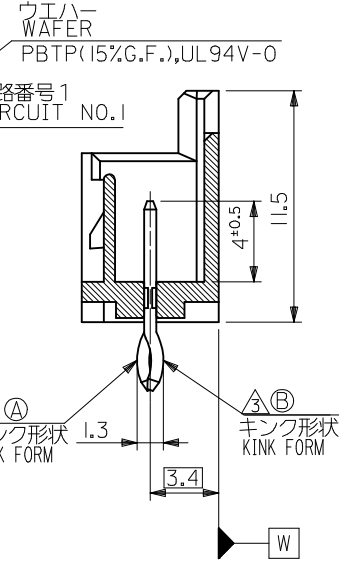
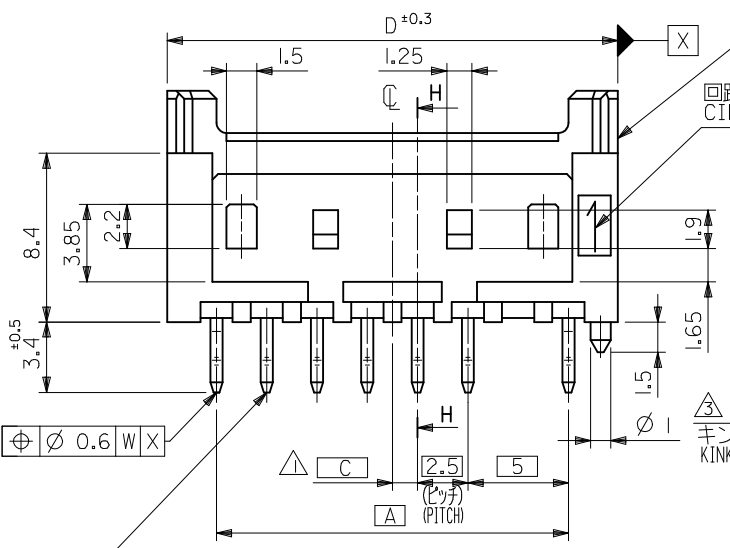
注記
NOTES

△ ウエハの ① から隣接するピンの ② までの位置を示す。
SHOW POSITION FROM ① OF WAFER TO ② OF ADJACENT PIN.

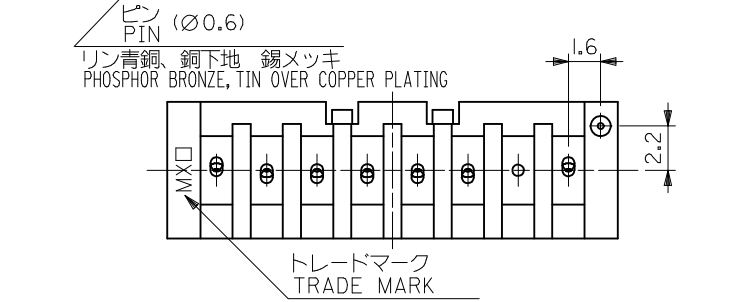
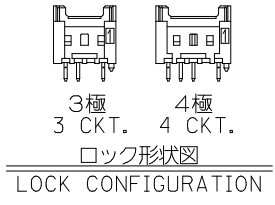
2. 嵌合相手：51102,51103 シリーズ
MATES WITH : 51102,51103 SERIES.

△ キングの形状は両サイドが ③、その他の極はすべて ④ 形状とする。
KINK FORM MORE THAN 2 CURCUIT:
PINS AT BOTH ENDS ARE KINK FORMED TO ③, THE OTHER PINS ARE KINK FORMED TO ④.

基板取付穴推奨寸法 (マウント面)
RECOMMENDED P.C.BOARD HOLE DIMENSION (MOUNTING SIDE)
($\tau=1.6$)



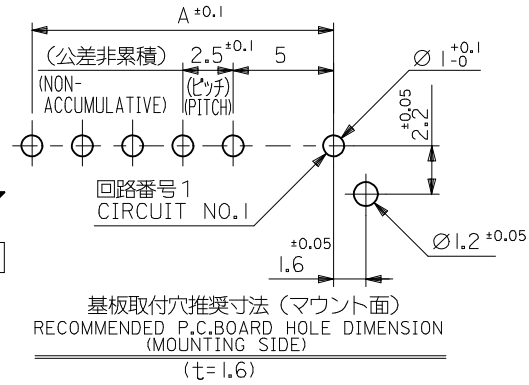
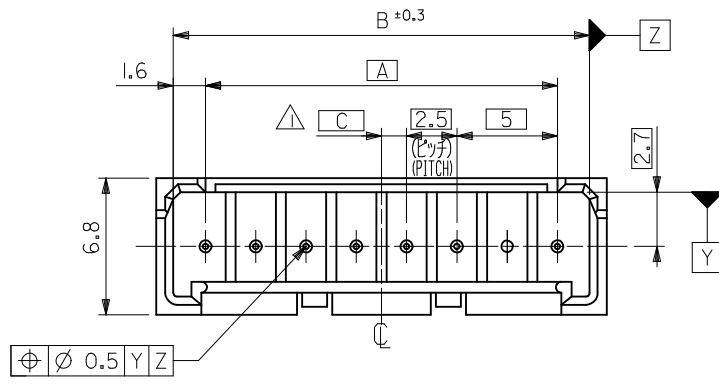
断面 H-H
SECT. H-H



24.9	2.5	23.2	20	53389-0810	8
19.9	2.5	18.2	15	53389-0610	6
12.4	2.5	10.7	7.5	53389-0310	3
D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

MODEL NO. 53389-***10

REVISED EC NO: J2017-0224 DRW: M. SHIKAWA 2016/10/12 CHKD: K. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±	DRAWN BY K. TOJO	DATE '92/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER 0.5 UNDER	±	CHECKED BY M. FUKUSHIMA	DATE '96/7/24			
	0.5 OVER 1.0 UNDER	±	APPROVED BY M. FUKUSHIMA	DATE '96/7/24			
	10 OVER 30 UNDER	±0.25	MATERIAL NO.	DOCUMENT NO.	SEE CHART	SD-53389-001	SHEET NO. 1 OF 1
30 OVER	±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

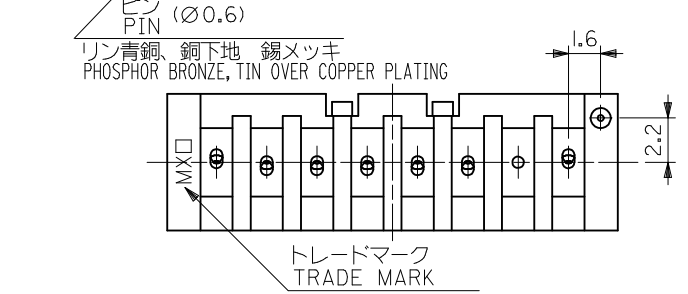
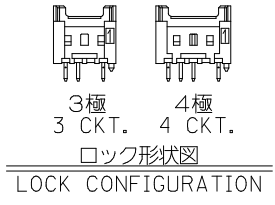
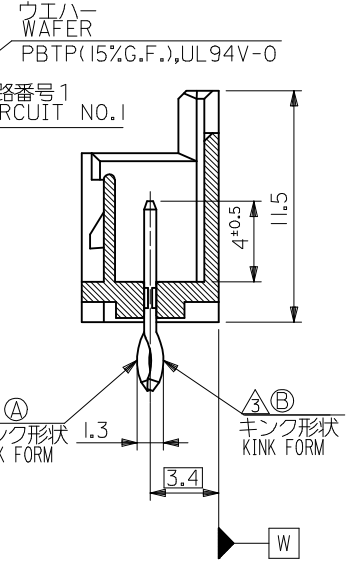
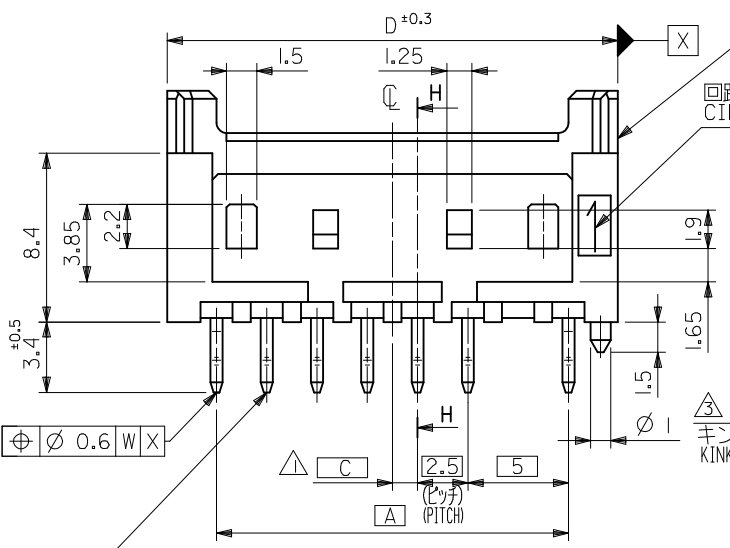


注記
NOTES

△ ウエハの ϕ から隣接するピンの ϕ までの位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PIN.

2. 嵌合相手: 51102, 51103 シリーズ
MATES WITH: 51102, 51103 SERIES.

△ キングの形状は両サイドが (A)、その他の極はすべて (B) 形状とする。
KINK FORM MORE THAN 2 CIRCUIT: PINS AT BOTH ENDS ARE KINK FORMED TO (A), THE OTHER PINS ARE KINK FORMED TO (B).



24.9	2.5	23.2	20	53389-0810	8
19.9	2.5	18.2	15	53389-0610	6
12.4	3.25	10.7	7.5	53389-0310	3
D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

REVISED EC NO: J2017-0224 DRW: M. SHIKAWA 2016/10/12 CHK: D. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±	DRAWN BY K. TOJO	DATE '92/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER 0.5 UNDER	±	CHECKED BY M. FUKUSHIMA	DATE '96/7/24			
	0.5 OVER 1.0 UNDER	±	APPROVED BY M. FUKUSHIMA	DATE '96/7/24			
10 OVER 30 UNDER	±0.25	MATERIAL NO.	DOCUMENT NO.	SEE CHART	SD-53389-001	SHEET NO. 1 OF 1	
30 OVER	±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
ANGULAR ±3 °							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							